

1-1932000-1 ✓ ACTIVE

DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 1-1932000-1

DDR3 DIMM, DIMM Sockets, Double Data Rate (DDR) 3, Board-to-Board, 240 Position, Through Hole - Solder, Vertical Module

Orientation

[View on TE.com >](#)



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM SOCKETS



DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

PCB Mounting Style: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM SOCKETS \(15\)](#)

## Features

### Product Type Features

|                                   |                          |
|-----------------------------------|--------------------------|
| Center Post                       | With                     |
| DRAM Type                         | Double Data Rate (DDR) 3 |
| Connector System                  | Board-to-Board           |
| Sealable                          | No                       |
| Connector & Contact Terminates To | Printed Circuit Board    |
| Product Type                      | Socket                   |

### Configuration Features

|                     |          |
|---------------------|----------|
| Center Key          | Center   |
| Number of Keys      | 1        |
| Number of Bays      | 2        |
| Number of Positions | 240      |
| Module Orientation  | Vertical |
| Keying              | Standard |



|                |   |
|----------------|---|
| Number of Rows | 2 |
|----------------|---|

### Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 1.5 V |
|--------------|-------|

### Body Features

|                        |         |
|------------------------|---------|
| Ejector Material Color | Natural |
|------------------------|---------|

|                         |       |
|-------------------------|-------|
| Retention Post Material | Brass |
|-------------------------|-------|

|                  |                        |
|------------------|------------------------|
| Ejector Material | High Temperature Nylon |
|------------------|------------------------|

|                  |           |
|------------------|-----------|
| Ejector Location | Both Ends |
|------------------|-----------|

|                |               |
|----------------|---------------|
| Latch Material | Thermoplastic |
|----------------|---------------|

|                 |             |
|-----------------|-------------|
| Module Key Type | Offset Left |
|-----------------|-------------|

|             |         |
|-------------|---------|
| Latch Color | Natural |
|-------------|---------|

|                         |        |
|-------------------------|--------|
| Retention Post Location | Center |
|-------------------------|--------|

|              |          |
|--------------|----------|
| Ejector Type | Standard |
|--------------|----------|

### Contact Features

|              |      |
|--------------|------|
| Socket Style | DIMM |
|--------------|------|

|                               |        |
|-------------------------------|--------|
| Contact Underplating Material | Nickel |
|-------------------------------|--------|

|   |     |
|---|-----|
| PCB Contact Termination Area Plating Material | Tin |
|---|-----|

|                       |              |
|-----------------------|--------------|
| Contact Base Material | Copper Alloy |
|-----------------------|--------------|

|                              |       |
|------------------------------|-------|
| Contact Current Rating (Max) | .75 A |
|------------------------------|-------|

|                                      |      |
|--------------------------------------|------|
| Contact Mating Area Plating Material | Gold |
|--------------------------------------|------|

|                                       |  |
|---------------------------------------|--|
| Contact Mating Area Plating Thickness | .38 $\mu\text{m}$ [15 $\mu\text{in}$ ] |
|---------------------------------------|--|

|                                       |   |
|---------------------------------------|---|
| Solder Tail Contact Plating Thickness | 3 $\mu\text{m}$ [118.1 $\mu\text{in}$ ] |
|---------------------------------------|---|

|             |             |
|-------------|-------------|
| Socket Type | Memory Card |
|-------------|-------------|

### Termination Features

|                 |               |
|-----------------|---------------|
| Insertion Style | Direct Insert |
|-----------------|---------------|

|                         |                  |
|-------------------------|------------------|
| Termination Post Length | 3.18 mm[.125 in] |
|-------------------------|------------------|

### Mechanical Attachment

|                     |      |
|---------------------|------|
| PCB Mount Retention | With |
|---------------------|------|

|                          |                     |
|--------------------------|---------------------|
| PCB Mount Retention Type | Retention Clip/Post |
|--------------------------|---------------------|

|                    |                       |
|--------------------|-----------------------|
| PCB Mounting Style | Through Hole - Solder |
|--------------------|-----------------------|

|                         |             |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

|                    |       |
|--------------------|-------|
| Boardlock Material | Brass |
|--------------------|-------|



|                |          |
|----------------|----------|
| Mounting Angle | Vertical |
|----------------|----------|

### Housing Features

|                    |                        |
|--------------------|------------------------|
| Centerline (Pitch) | 1 mm[.039 in]          |
| Housing Material   | High Temperature Nylon |
| Housing Color      | Black                  |

### Dimensions

|                                |                 |
|--------------------------------|-----------------|
| Center Retention Hole Diameter | 1.8 mm[.07 in]  |
| Height Above PC Board          | 23.1 mm[.9 in]  |
| Row-to-Row Spacing             | 1.9 mm[.075 in] |

### Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 155 °C[-67 – 311 °F] |
|-----------------------------|----------------------------|

### Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

### Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

### Packaging Features

|                    |      |
|--------------------|------|
| Packaging Method   | Tray |
| Packaging Quantity | 50   |

## Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

|   |   |
|---|---|
| EU RoHS Directive 2011/65/EU                  | Compliant   |
| EU ELV Directive 2000/53/EC                   | Compliant   |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold   |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUN 2020 (209)<br>Candidate List Declared Against: JUN 2020 (209)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.  |
| Solder Process Capability                     | Wave solder capable to 260°C  |

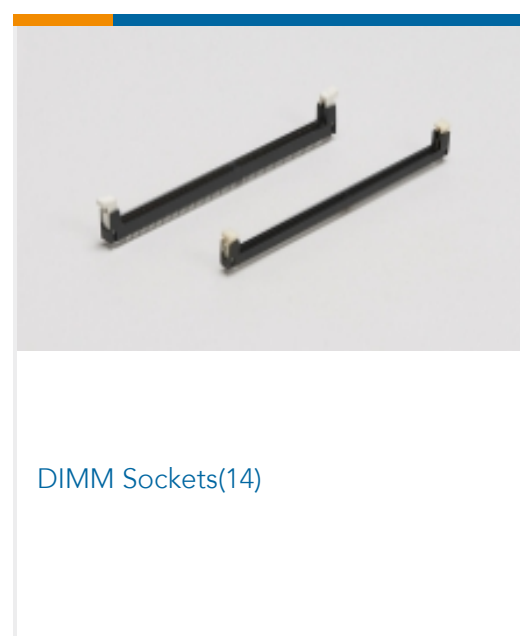
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

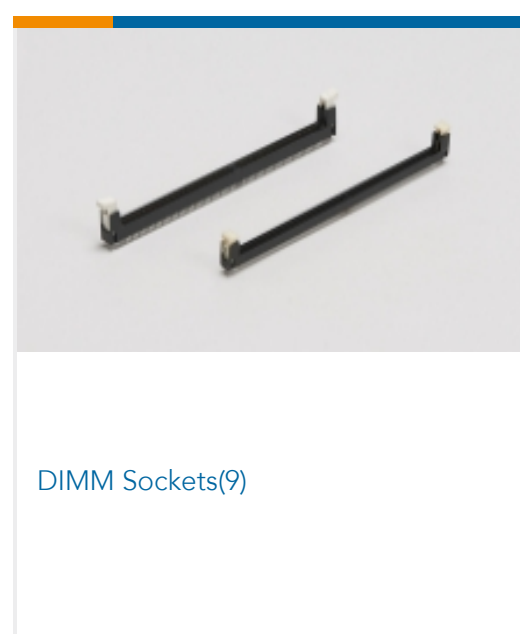
## Compatible Parts



## Also in the Series | DDR3 DIMM



## Also in the Series | DDR3 SO DIMM



## Customers Also Bought



## Documents

### Product Drawings

#### VERTICAL DDR3 DIMM, 240 POSITION

English

### CAD Files

#### 3D PDF

3D

#### Customer View Model

[ENG\\_CVM\\_CVM\\_1-1932000-1\\_F.2d\\_dxf.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_1-1932000-1\\_F.3d\\_igs.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_1-1932000-1\\_F.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Datasheets & Catalog Pages



## 6-1773457-3\_DDR3\_DIMM\_SOCKETS

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### Product Specifications

#### Product Specification

English

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### Product Environmental Compliance

#### MD\_1-1932000-1\_01302018150\_dmtec

English

#### MD\_1-1932000-1\_01302018150\_dmtec

English